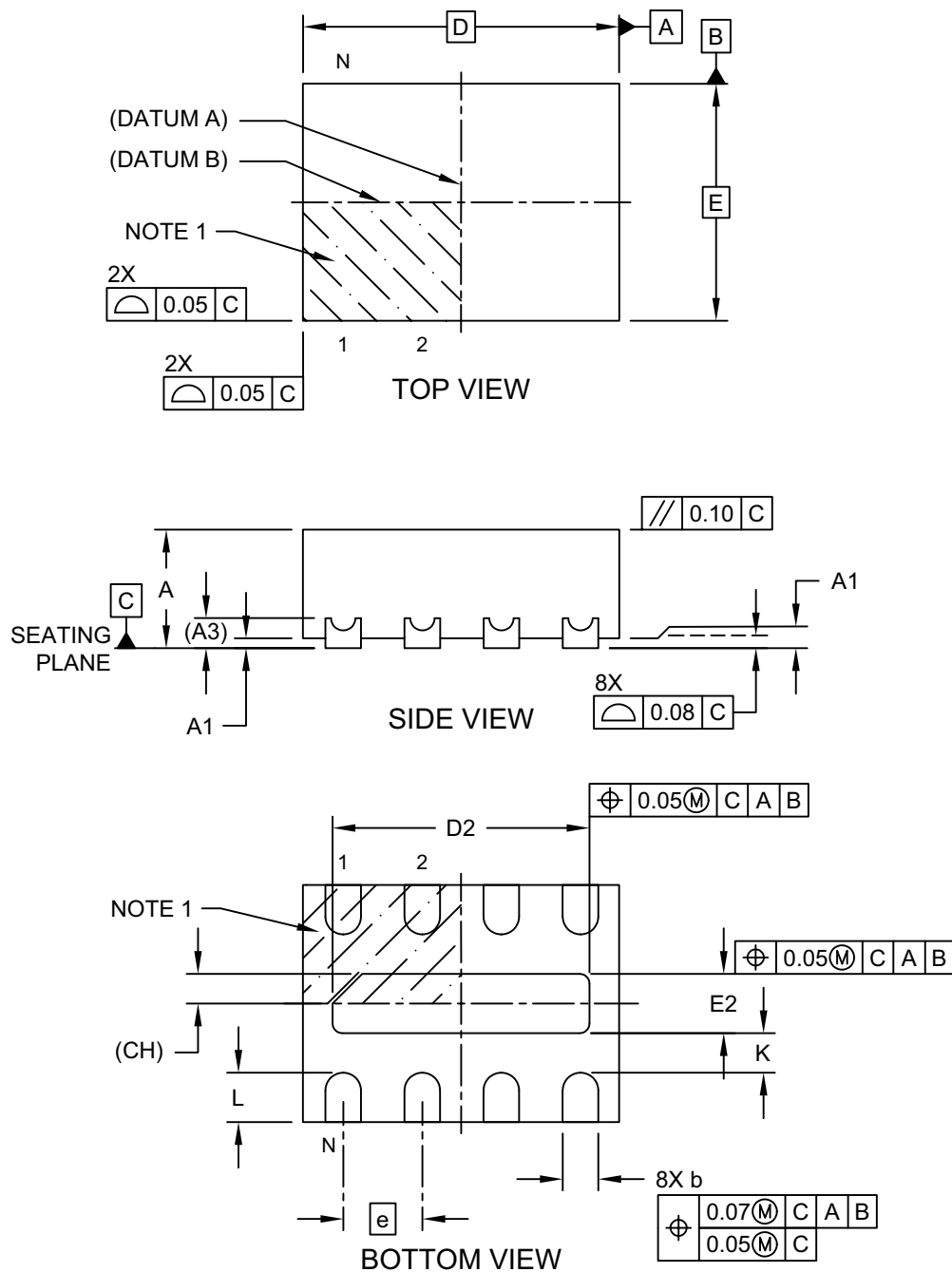


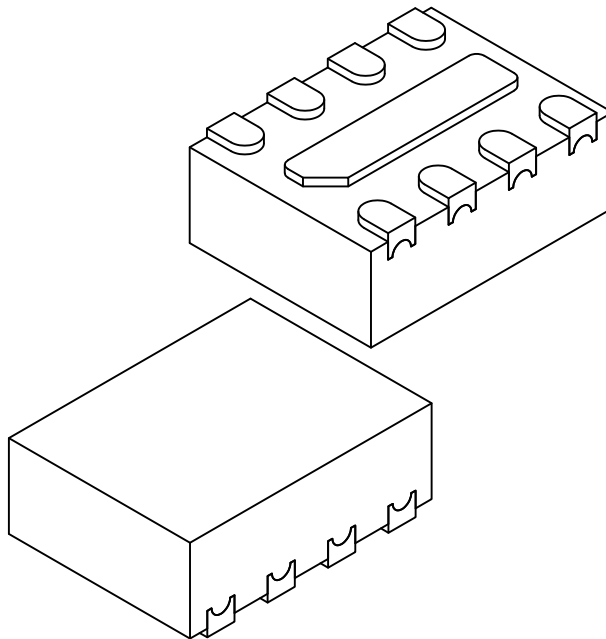
8-Lead Ultra Thin Dual Flat, No Lead Package (HJA) - 1.6 x 1.2 x 0.6 mm Body [UDFN] Micrel Legacy Package TMLF1216D-08L

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



8-Lead Ultra Thin Dual Flat, No Lead Package (HJA) - 1.6 x 1.2 x 0.6 mm Body [UDFN] Micrel Legacy Package TMLF1216D-08L

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



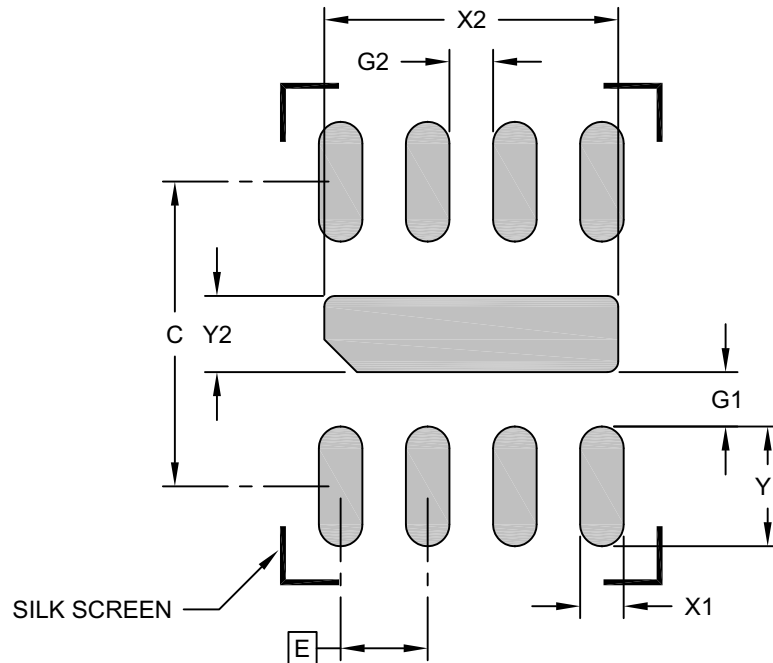
Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Terminals	N	8		
Pitch	e	0.40 BSC		
Overall Height	A	0.50	0.55	0.60
Standoff	A1	0.00	0.02	0.05
Terminal Thickness	A3	0.152 REF		
Overall Length	D	1.60 BSC		
Exposed Pad Length	D2	1.25	1.30	1.35
Overall Width	E	1.20 BSC		
Exposed Pad Width	E2	0.25	0.30	0.35
Exposed Pad Index Chamfer	CH	0.15 REF		
Terminal Width	b	0.13	0.18	0.23
Terminal Length	L	0.20	0.25	0.30
Terminal-to-Exposed-Pad	K	0.20	—	—

Notes:

- Pin 1 visual index feature may vary, but must be located within the hatched area.
- Package is saw singulated
- Dimensioning and tolerancing per ASME Y14.5M
 - BSC: Basic Dimension. Theoretically exact value shown without tolerances.
 - REF: Reference Dimension, usually without tolerance, for information purposes only.

8-Lead Ultra Thin Dual Flat, No Lead Package (HJA) - 1.6 x 1.2 x 0.6 mm Body [UDFN] Micrel Legacy Package TMLF1216D-08L

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E	0.40 BSC		
Center Pad Width	X2			1.35
Center Pad Length	Y2			0.35
Contact Pad Spacing	C		1.40	
Contact Pad Width (X8)	X1			0.20
Contact Pad Length (X8)	Y1			0.55
Contact Pad to Center Pad (X8)	G1	0.25		
Contact Pad to Contact Pad (X6)	G2	0.20		

Notes:

- Dimensioning and tolerancing per ASME Y14.5M
BSC: Basic Dimension. Theoretically exact value shown without tolerances.
- For best soldering results, thermal vias, if used, should be filled or tented to avoid solder loss during reflow process

Microchip Technology Drawing C04-3153 Rev A